

(43) International Publication Date
24 July 2025 (24.07.2025)



(10) International Publication Number
WO 2025/155655 A1



(51) **International Patent Classification:**
C23C 14/50 (2006.01) C23C 14/34 (2006.01)

(21) **International Application Number:**
PCT/US2025/011773

(22) **International Filing Date:**
16 January 2025 (16.01.2025)

(25) **Filing Language:** English

(26) **Publication Language:** English

(30) **Priority Data:**
18/417,160 19 January 2024 (19.01.2024) US

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(81) Designated States (*unless otherwise indicated, for every kind of national protection available*): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE, KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, MG, MK, MN, MU, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UY, UZ, VC, VN, WS, ZA, ZM, ZW.

(84) Designated States (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, CV, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SC, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, ME, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Published:
— *with international search report (Art. 21(3))*

(54) Title: DIELECTRIC DEPOSITION RING WITH FINS FOR PHYSICAL VAPOR DEPOSITION

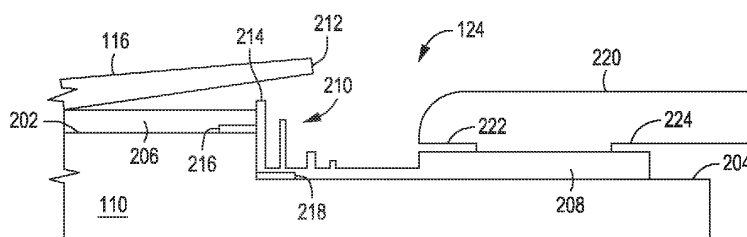


FIG. 2

(57) Abstract: Methods and apparatus for processing a substrate are provided herein. In some embodiments, a process kit for a substrate support includes: a dielectric plate having a lower surface configured to cover a support surface of the substrate support and an upper surface configured to support a substrate; and a dielectric deposition ring surrounding the dielectric plate and configured to cover a portion of the substrate support disposed radially outward of the support surface.



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